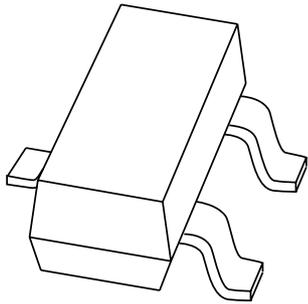


# DATA SHEET



# BAP1321-04

## FEATURES

- High voltage, current controlled
- RF resistor for RF attenuators and switches
- Low diode capacitance
- Low diode forward resistance
- Very low series inductance
- For applications up to 3 GHz.

## APPLICATIONS

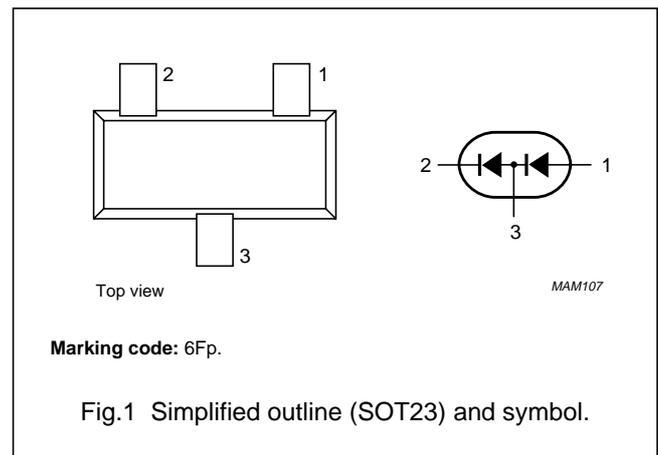
- RF attenuators and switches.

## DESCRIPTION

Two planar PIN diodes in series configuration in a SOT23 small SMD plastic package.

## PINNING

PIN	DESCRIPTION
1	anode
2	cathode
3	common connection



## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
<b>Per diode</b>					
$V_R$	continuous reverse voltage		–	60	V
$I_F$	continuous forward current		–	100	mA
$P_{tot}$	total power dissipation	$T_s \leq 90\text{ °C}$	–	250	mW
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	junction temperature		–65	+150	°C

# BAP1321-04

## ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
<b>Per diode</b>					
$V_F$	forward voltage	$I_F = 50\text{ mA}$	0.95	1.1	V
$I_R$	reverse leakage current	$V_R = 60\text{ V}$	–	100	nA
$C_d$	diode capacitance	$V_R = 0; f = 1\text{ MHz}$	0.42	–	pF
		$V_R = 1\text{ V}; f = 1\text{ MHz}$	0.375	0.45	pF
		$V_R = 20\text{ V}; f = 1\text{ MHz}$	0.275	0.325	pF
$r_D$	diode forward resistance	$f = 100\text{ MHz}$ ; note 1			
		$I_F = 0.5\text{ mA}$	3.4	5.0	$\Omega$
		$I_F = 1\text{ mA}$	2.4	3.6	$\Omega$
		$I_F = 10\text{ mA}$	1.2	1.8	$\Omega$
$ S_{21} ^2$	isolation	$V_R = 0; f = 900\text{ MHz}$	15.7	–	dB
		$V_R = 0; f = 1800\text{ MHz}$	10.5	–	dB
		$V_R = 0; f = 2450\text{ MHz}$	7.9	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 0.5\text{ mA}; f = 900\text{ MHz}$	0.27	–	dB
		$I_F = 0.5\text{ mA}; f = 1800\text{ MHz}$	0.35	–	dB
		$I_F = 0.5\text{ mA}; f = 2450\text{ MHz}$	0.43	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 1\text{ mA}; f = 900\text{ MHz}$	0.21	–	dB
		$I_F = 1\text{ mA}; f = 1800\text{ MHz}$	0.29	–	dB
		$I_F = 1\text{ mA}; f = 2450\text{ MHz}$	0.37	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 10\text{ mA}; f = 900\text{ MHz}$	0.14	–	dB
		$I_F = 10\text{ mA}; f = 1800\text{ MHz}$	0.21	–	dB
		$I_F = 10\text{ mA}; f = 2450\text{ MHz}$	0.29	–	dB
$ S_{21} ^2$	insertion loss	$I_F = 100\text{ mA}; f = 900\text{ MHz}$	0.10	–	dB
		$I_F = 100\text{ mA}; f = 1800\text{ MHz}$	0.18	–	dB
		$I_F = 100\text{ mA}; f = 2450\text{ MHz}$	0.26	–	dB
$\tau_L$	charge carrier life time	when switched from $I_F = 10\text{ mA}$ to $I_R = 6\text{ mA}$ ; $R_L = 100\text{ }\Omega$ ; measured at $I_R = 3\text{ mA}$	0.5	–	$\mu\text{s}$
$L_S$	series inductance	$I_F = 100\text{ mA}; f = 100\text{ MHz}$	1.4	–	nH

### Note

1. Guaranteed on AQL basis: inspection level S4, AQL 1.0.

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to soldering point	220	K/W